

N-Channel Power MOSFET

60V, 54A, 12mΩ

FEATURES

- Low R_{DS(ON)} to minimize conductive losses
- Logic level
- Low gate charge for fast power switching
- 100% UIS and R_g tested
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

KEY PERFORMANCE PARAMETERS				
PARAMETER		VALUE	UNIT	
V_{DS}		60	V	
R _{DS(on)} (max)	V _{GS} = 10V	12		
	$V_{GS} = 4.5V$	15	mΩ	
Q_g		18	nC	



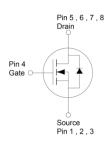




APPLICATIONS

- BLDC Motor Control
- Battery Power Management
- DC-DC converter
- Secondary Synchronous Rectification





Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	60	V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current (Note 1)	$T_C = 25^{\circ}C$	l _D	54	Α	
	$T_{C} = 25^{\circ}C$ $T_{A} = 25^{\circ}C$		10		
Pulsed Drain Current		I _{DM}	216	А	
Single Pulse Avalanche Current (Note 2)		I _{AS}	19	А	
Single Pulse Avalanche Energy (Note 2)		E _{AS}	54	mJ	
Total Power Dissipation	$T_C = 25^{\circ}C$	P _D	69	W	
	$T_{\rm C} = 125^{\circ}{\rm C}$		14		
Total Power Dissipation	$T_A = 25$ °C	В	2.6	W	
	T _A = 125°C	P_{D}	0.5		
Operating Junction and Storage Temp	perature Range	T_{J}, T_{STG}	- 55 to +150	°C	

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction to Case Thermal Resistance	R _{eJC}	1.8	°C/W	
Junction to Ambient Thermal Resistance	R _{OJA}	48	°C/W	

Thermal Performance Note: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

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ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV _{DSS}	60			V
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	$V_{GS(TH)}$	1.2	1.7	2.5	V
Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	I _{GSS}			±100	nA
Drain-Source Leakage Current	$V_{GS} = 0V, V_{DS} = 60V$				1	μА
	$V_{GS} = 0V, V_{DS} = 60V$ $T_{J} = 125^{\circ}C$	I _{DSS}			100	
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 10A$			9.6	12	mΩ
(Note 3)	$V_{GS} = 4.5V, I_D = 9A$	R _{DS(on)}		11	15	
Forward Transconductance (Note 3)	$V_{DS} = 5V, I_{D} = 10A$	9 _{fs}		36		S
Dynamic (Note 4)						
Total Gate Charge	$V_{GS} = 10V, V_{DS} = 30V,$ $I_{D} = 10A$	Q_g		36.5		
Total Gate Charge	$V_{GS} = 4.5V, V_{DS} = 30V,$	Q_g		18		nC
Gate-Source Charge		Q_{gs}		6		
Gate-Drain Charge	$I_D = 9A$	Q_{gd}		7.5		
Input Capacitance		C _{iss}		2116		
Output Capacitance	$V_{GS} = 0V$, $V_{DS} = 30V$	C _{oss}		136		pF
Reverse Transfer Capacitance	f = 1.0MHz	C _{rss}		85		
Gate Resistance	f = 1.0MHz	R_g	0.5	1.6	3.2	Ω
Switching (Note 4)						
Turn-On Delay Time		t _{d(on)}		6.5		
Turn-On Rise Time	$V_{GS} = 10V, V_{DS} = 30V,$ $I_{D} = 10A, R_{G} = 2\Omega,$	t _r		13		
Turn-Off Delay Time		t _{d(off)}		26		ns
Turn-Off Fall Time		t _f		7		
Source-Drain Diode						
Forward Voltage (Note 3)	$V_{GS} = 0V, I_{S} = 10A$	V_{SD}			1	V
Reverse Recovery Time	I _S = 10A ,	t _{rr}		18		ns
Reverse Recovery Charge	dl/dt = 100A/µs	Q _{rr}		14		nC

Notes:

- 1. Silicon limited current only.
- 2. L = 0.3mH, $V_{GS} = 10$ V, $V_{DD} = 30$ V, $R_G = 25\Omega$, $I_{AS} = 19$ A, Starting $T_J = 25$ °C
- 3. Pulse test: Pulse Width \leq 300µs, duty cycle \leq 2%.
- 4. Switching time is essentially independent of operating temperature.

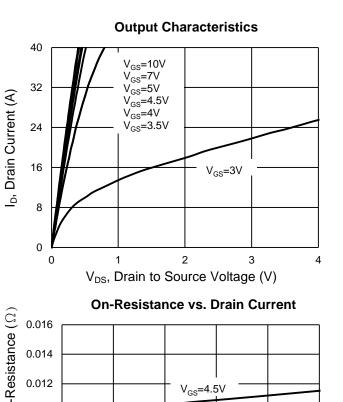
ORDERING INFORMATION

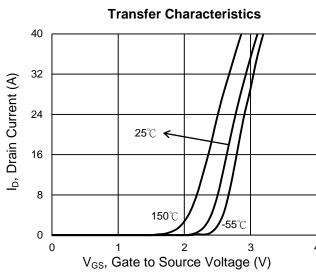
PART NO.	PACKAGE	PACKING
TSM120N06LCR RLG	PDFN56	2500pcs / 13" Reel

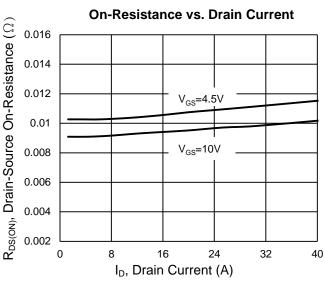


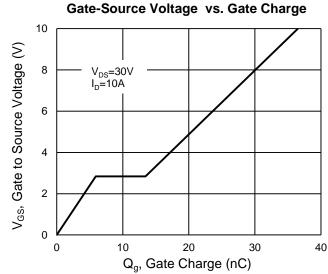
CHARACTERISTICS CURVES

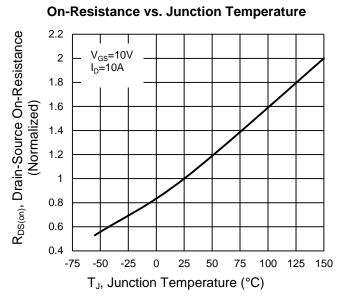
 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

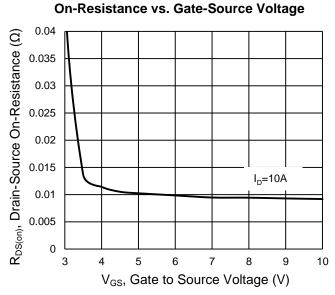








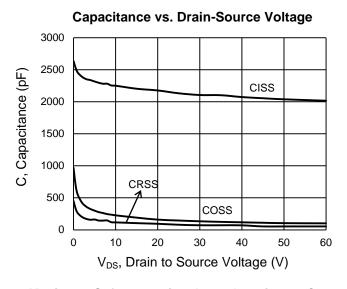


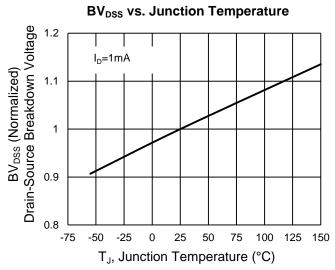


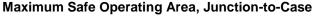


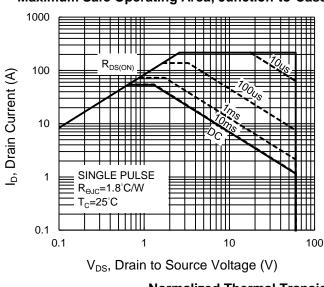
CHARACTERISTICS CURVES

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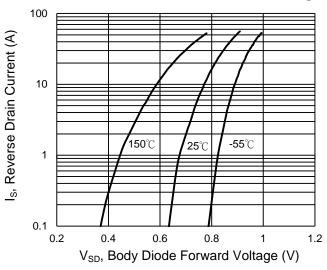




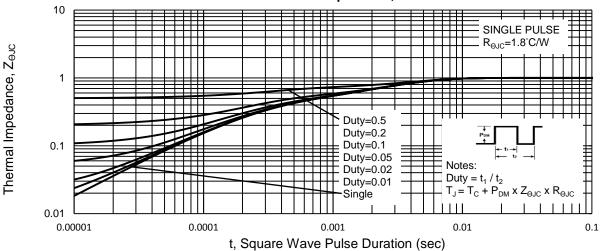


Normalized Effective Transient

Source-Drain Diode Forward Current vs. Voltage







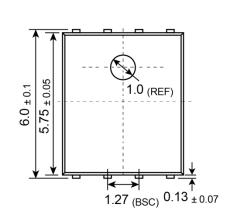
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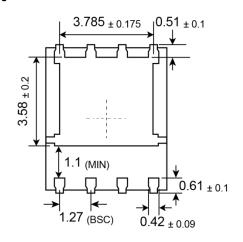


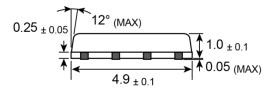


PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

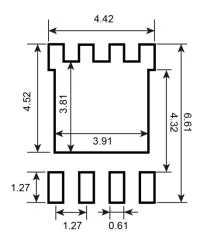
PDFN56







SUGGESTED PAD LAYOUT (Unit: Millimeters)



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MARKING DIAGRAM



G = Halogen Free

Y = Year Code

WW = Week Code (01~52)

F = Factory Code



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